

L Number	Hits	Search Text	DB	Time stamp
1	2621640	chip dice semiconductor ic die (integrated adj circuit) microchipmcm csp mems opticelectronic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:23
2	3674283	substrate carrier cb pcb board (printed adj4 board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:24
3	703686	flipchip (flip adj chip) bump ball bga	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:25
4	1957976	(non adj (thermoset thermosetting)) thermoplastic polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:26
5	125316	((non adj (thermoset thermosetting)) thermoplastic polymer ) with (adhesive adhesion sphere)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:27
6	1920	(flipchip (flip adj chip) bump ball bga) same ((non adj (thermoset thermosetting)) thermoplastic polymer ) with (adhesive adhesion sphere))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:28
7	1002	((flipchip (flip adj chip) bump ball bga) same ((non adj (thermoset thermosetting)) thermoplastic polymer ) with (adhesive adhesion sphere))) and (chip dice semiconductor ic die (integrated adj circuit) microchipmcm csp mems opticelectronic) and (substrate carrier cb pcb board (printed adj4 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:29
8	560	(remove removal removable) and (((flipchip (flip adj chip) bump ball bga) same ((non adj (thermoset thermosetting)) thermoplastic polymer ) with (adhesive adhesion sphere))) and (chip dice semiconductor ic die (integrated adj circuit) microchipmcm csp mems opticelectronic) and (substrate carrier cb pcb board (printed adj4 board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:29